

67,200-506; TSMC 00-804
Serial Number 09/920,911

#11
Response
5-29-03
and

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TO: Assistant Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

FAX RECEIVED

FROM: Tung & Associates
838 West Long Lake Road - Suite 120
Bloomfield Hills, MI 48302

MAY 23 2003

TECHNOLOGY CENTER 2800

DATE: 16 May 2003

REF: Applicant : Yu et al. Filing Date : 2 August 2001
Serial No : 09/920,911 Att'y No. : 67,200-506
Art Unit : 2812 Examiner : Richard A. Booth
Title : Thermal Compensation Method for Forming Semiconductor
Integrated Circuit Microelectronic Fabrication

RESPONSE TO OFFICE ACTION MADE FINAL

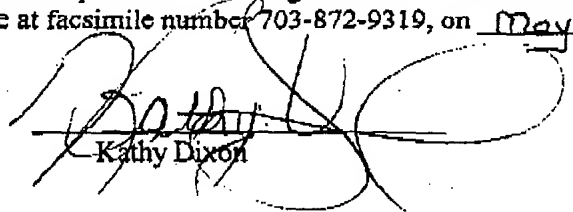
Sir:

In response to an office action mailed on 26 March 2003 and made FINAL, please consider the following remarks directed towards the above referenced patent application.

There are no amendments to the specification, claims or the drawings. A listing of the claims begins on page 2 of this paper. Remarks begin on page 6 of this paper.

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office at facsimile number 703-872-9319, on May 23, 2003.


Kathy Dixon